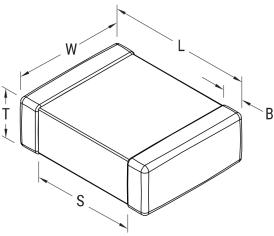


C0805F104M3RAC7210

SMD Comm X7R FO, Ceramic, 0.1 uF, 20%, 25 VDC, X7R, SMD, MLCC, Open Mode, Temperature Stable, 0805



Click here for the 3D model.

Dimensions	
Chip Size	0805
L	2mm +/-0.2mm
W	1.25mm +/-0.2mm
Т	1.25mm +/-0.15mm
S	0.7mm MIN
В	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	10000

General Information	
Series	SMD Comm X7R FO
Style	SMD Chip
Description	SMD, MLCC, Open Mode, Temperature Stable
Features	Open Mode, Temperature Stable
RoHS	Yes
Termination	Tin
Marking	false
AEC-Q200	No
Typical Component Weight	21 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.1 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	20%
Voltage DC	25 VDC
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	3.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	10 GOhms

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